

AMENDMENTS TO THE CLAIMS

Claim 1 (Previously Presented): A ceramic heater for a semiconductor-producing/examining device, the ceramic heater comprising

a ceramic substrate having a disc form including two opposing surfaces; and

a resistance heating element on one of the two opposing surfaces of the ceramic substrate or inside the ceramic substrate, wherein

the ceramic substrate comprises a non-oxide ceramic containing 0.05 to 5% by weight of oxygen; and

the non-oxide ceramic has a maximum pore diameter of 5 μm or less.

Claim 2 (Previously Presented): The ceramic heater according to claim 1, wherein said non-oxide ceramic is a nitride ceramic.

Claim 3 (Previously Presented): The ceramic heater according to claim 1, wherein said non-oxide ceramic is a carbide ceramic.

Claim 4 (Canceled)

Claim 5 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate has a porosity of 5% or less.

Claim 6 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate is capable of use within the temperature range of 100 to 700 C.

Claim 7 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate has a thickness of 25 mm or less, and a diameter of 200 mm or more.

Claim 8 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate has a plurality of through holes into which lifter pins for a semiconductor wafer are capable of being inserted.

Claim 9 (Canceled)

Claim 10 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate contains oxygen in an amount of 0.1 to 5% by weight.

Claim 11 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate comprises an alkali metal oxide, an alkali earth metal oxide, or a rare earth element oxide.

Claim 12 (Previously Presented): The ceramic heater according to claim 1, wherein an electrostatic electrode or an RF electrode is embedded inside the ceramic substrate.

Claim 13 (Previously Presented): The ceramic heater according to claim 1, wherein said heating element is a Peltier device.

Claim 14 (Previously Presented): The ceramic heater according to claim 1, wherein said heating element is selected from the group consisting of a conductive ceramic, a metal foil, a metal sintered body, and a metal wire.

Claim 15 (Previously Presented): The ceramic heater according to claim 1, wherein a chuck top conductor layer is formed on the surface of said ceramic substrate.

Claim 16 (Previously Presented): The ceramic heater according to claim 1, wherein said ceramic substrate contains BN.

Claim 17 (Canceled)